

# **KP-2012SGC**

2.0 x 1.25 mm SMD Chip LED Lamp



# **DESCRIPTION**

• The Super Bright Green source color devices are made with Gallium Phosphide Green Light Emitting

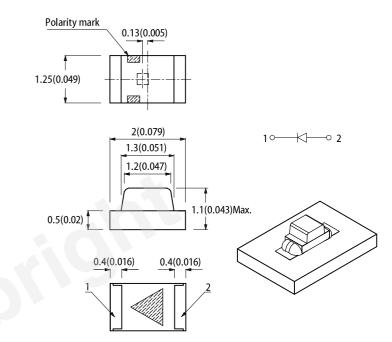
# **FEATURES**

- 2.0 mm x 1.25 mm SMD LED, 1.1 mm thickness
- Low power consumption
- · Wide viewing angle
- · Ideal for backlight and indicator
- Package: 2000 pcs / reel
- Moisture sensitivity level: 3
- · RoHS compliant

# **APPLICATIONS**

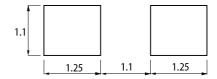
- Backlight
- · Status indicator
- · Home and smart appliances
- · Wearable and portable devices
- · Healthcare applications

# **PACKAGE DIMENSIONS**



# **RECOMMENDED SOLDERING PATTERN**

(units: mm; tolerance:  $\pm$  0.1)



- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is ±0.1(0.004") unless otherwise noted.
  3. The specifications, characteristics and technical data described in the datasheet are subject to
- change without prior notice.

  4. The device has a single mounting surface. The device must be mounted according to the specifications.

# **SELECTION GUIDE**

Part Number	Emitting Color (Material)	Lens Type	Iv (mcd) @ 20mA [2]		Viewing Angle [1]
			Min.	Тур.	201/2
KP-2012SGC	Super Bright Green (GaP)	Water Clear	5	12	160°

Notes.

1. 01/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.

2. Luminous intensity / luminous flux: +/-15%.

3. Luminous intensity value is traceable to CIE127-2007 standards.





# ELECTRICAL / OPTICAL CHARACTERISTICS at T<sub>A</sub>=25°C

Danamatan	Comple at	Fortisting Outer	Value		1114
Parameter	Symbol	Emitting Color	Тур.	Max.	Unit
Wavelength at Peak Emission I <sub>F</sub> = 20mA	$\lambda_{peak}$	Super Bright Green	565	-	nm
Dominant Wavelength I <sub>F</sub> = 20mA	λ <sub>dom</sub> <sup>[1]</sup>	Super Bright Green	568	-	nm
Spectral Bandwidth at 50% $\Phi$ REL MAX I <sub>F</sub> = 20mA	Δλ	Super Bright Green	30	-	nm
Capacitance	С	Super Bright Green	15	-	pF
Forward Voltage I <sub>F</sub> = 20mA	V <sub>F</sub> <sup>[2]</sup>	Super Bright Green	2.2	2.5	V
Reverse Current (V <sub>R</sub> = 5V)	I <sub>R</sub>	Super Bright Green	-	10	μA
Temperature Coefficient of $\lambda_{peak}$ $I_F$ = 20mA, -10°C $\leq$ T $\leq$ 85°C	$TC_{\lambdapeak}$	Super Bright Green	0.12	-	nm/°C
Temperature Coefficient of $\lambda_{dom}$ $I_F$ = 20mA, -10°C $\leq T \leq 85^{\circ}C$	$TC_{\lambda dom}$	Super Bright Green	0.08	-	nm/°C
Temperature Coefficient of $V_F$ $I_F$ = 20mA, -10°C $\leq$ T $\leq$ 85°C	TC <sub>V</sub>	Super Bright Green	-2	-	mV/°C

## Notes:

# ABSOLUTE MAXIMUM RATINGS at T<sub>A</sub>=25°C

Parameter	Symbol	Value	Unit
Power Dissipation	P <sub>D</sub>	62.5	mW
Reverse Voltage	V <sub>R</sub>	5	V
Junction Temperature	Tj	110	°C
Operating Temperature	T <sub>op</sub>	-40 to +85	°C
Storage Temperature	T <sub>stg</sub>	-40 to +85	°C
DC Forward Current	I <sub>F</sub>	25	mA
Peak Forward Current	I <sub>FM</sub> <sup>[1]</sup>	140	mA
Electrostatic Discharge Threshold (HBM)	-	8000	V
Thermal Resistance (Junction / Ambient)	R <sub>th JA</sub> [2]	390	°C/W
Thermal Resistance (Junction / Solder point)	R <sub>th JS</sub> [2]	240	°C/W

Notes:
1. 1/10 Duty Cycle, 0.1ms Pulse Width.
2.  $R_{\rm B, LS}$  Results from mounting on PC board FR4 (pad size  $\geq$  16 mm<sup>2</sup> per pad).
3. Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity – Ref JEDEC/JESD625-A and JEDEC/J-STD-033.



Notes:

1. The dominant wavelength (λd) above is the setup value of the sorting machine. (Tolerance λd: ±1nm.)

2. Forward voltage: ±0.1V.

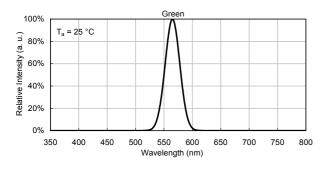
3. Wavelength value is traceable to CIE127-2007 standards.

4. Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

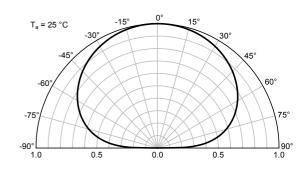
# **Kingbright**

## **TECHNICAL DATA**

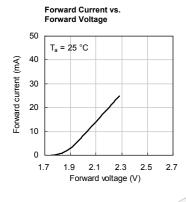
## **RELATIVE INTENSITY vs. WAVELENGTH**

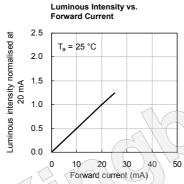


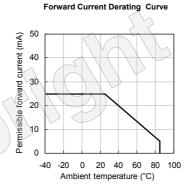
## **SPATIAL DISTRIBUTION**

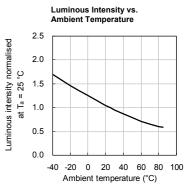


# **SUPER BRIGHT GREEN**

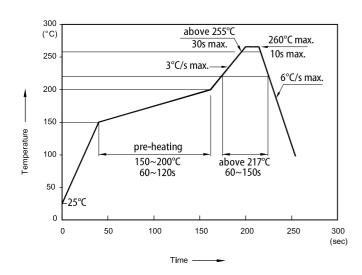






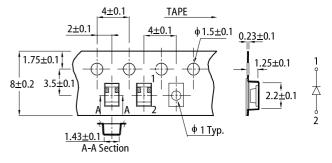


## REFLOW SOLDERING PROFILE for LEAD-FREE SMD PROCESS

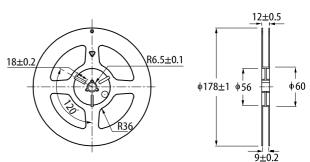


- 1. Don't cause stress to the LEDs while it is exposed to high temperature.
  2. The maximum number of reflow soldering passes is 2 times.
  3. Reflow soldering is recommended. Other soldering methods are not recommended as they might cause damage to the product

## TAPE SPECIFICATIONS (units:mm)

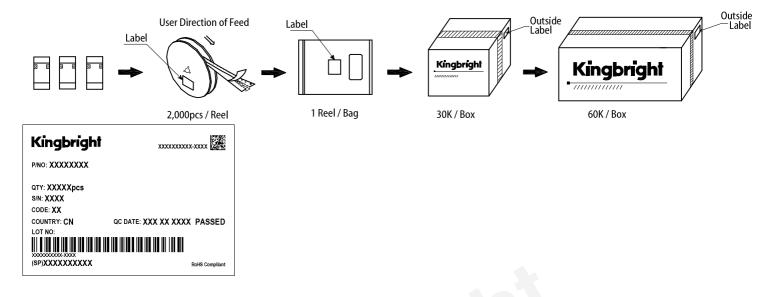


# **REEL DIMENSION** (units: mm)





# **PACKING & LABEL SPECIFICATIONS**



- PRECAUTIONARY NOTES

  1. The information included in this document reflects representative usage scenarios and is intended for technical reference only.
- The part number, type, and specifications mentioned in this document are subject to future change and improvement without notice. Before production usage customer should refer to
- the latest datasheet for the updated specifications.

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